

Silicone Thermal Putty Pad / XK-P50-Putty

Introduction

High thermal performance and reliability for irregular surface, excellent flowability and gap filling capacity under low bearing capacity and high compressive load

Features

- High reliability
- High compressibility
- Low bearing capacity



1. Product properties

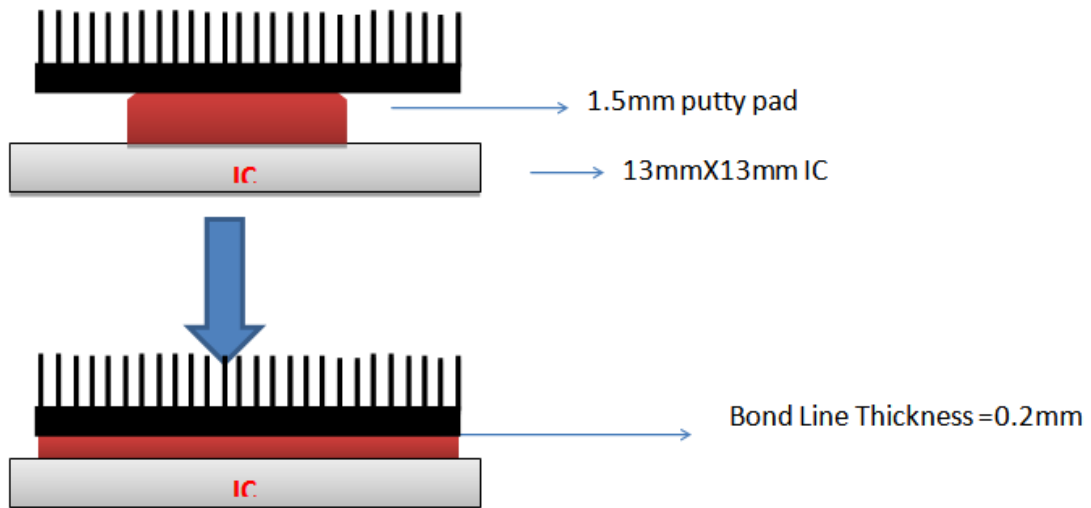
	XK-P50-P	Unit	Test Method
Thickness	1.0/ 1.5	mm	
Color	DarkRed		Visual
Construction	Silicone		
Op. temp. range	-45~150	°C	
Density	3.2	g/cm ³	ASTM D792
Thermal Conductivity	5.0	W/mK	ASTM D5470
Breakdown Voltage	>10	KV/mm	ASTM D149
Volume Resistance	10 ¹⁰	Ohm-cm	ASTM D257
Total Mass Loss	<0.4%	%	ASTM E595
Tensile strength	Na	Psi	ASTM D412
Elongation	Na	%	ASTM D412
Flame Rating	V-0		UL-94
REACH/RoHS Compliant	Yes		REACH/ RoHS

2. Thermal properties

	XK-P50-P
RA	Kin2/W
compress 30%	0.24
compress 40%	0.22
compress 50%	0.20
compress 70%	0.15
compress 90%	0.12

3. The Compression Load

	XK-P50-P
	Pressure(psi)
compress 30%	11
compress 40%	27
compress 50%	46
compress 70%	56
compress 90%	77



$$\begin{aligned}
 X &= \sqrt{(BLT \times IC \text{ Area}) / 1.5mm} \\
 &= \sqrt{(0.2mm \times 13mm \times 13mm) / 1.5mm} \\
 &= 4.7
 \end{aligned}$$

USE 5mm X 5mm @ 1.5mm Thickness